

PiBond – Who we are

Innovative technology company with strong R&D capabilities and a range of products commercialized. We are one of the only European suppliers of EUV lithography materials.

PiBond's materials have been adopted in the latest semiconductor devices globally.

Audited supplier track record to the semiconductor industry from our 3000 square meter PPT (*parts per trillion*) Clean Room production facility in Finland.



RESPONSIBLE CARE®
OUR COMMITMENT TO SUSTAINABILITY



PiBond

3,000 m² of space

State of the art automation

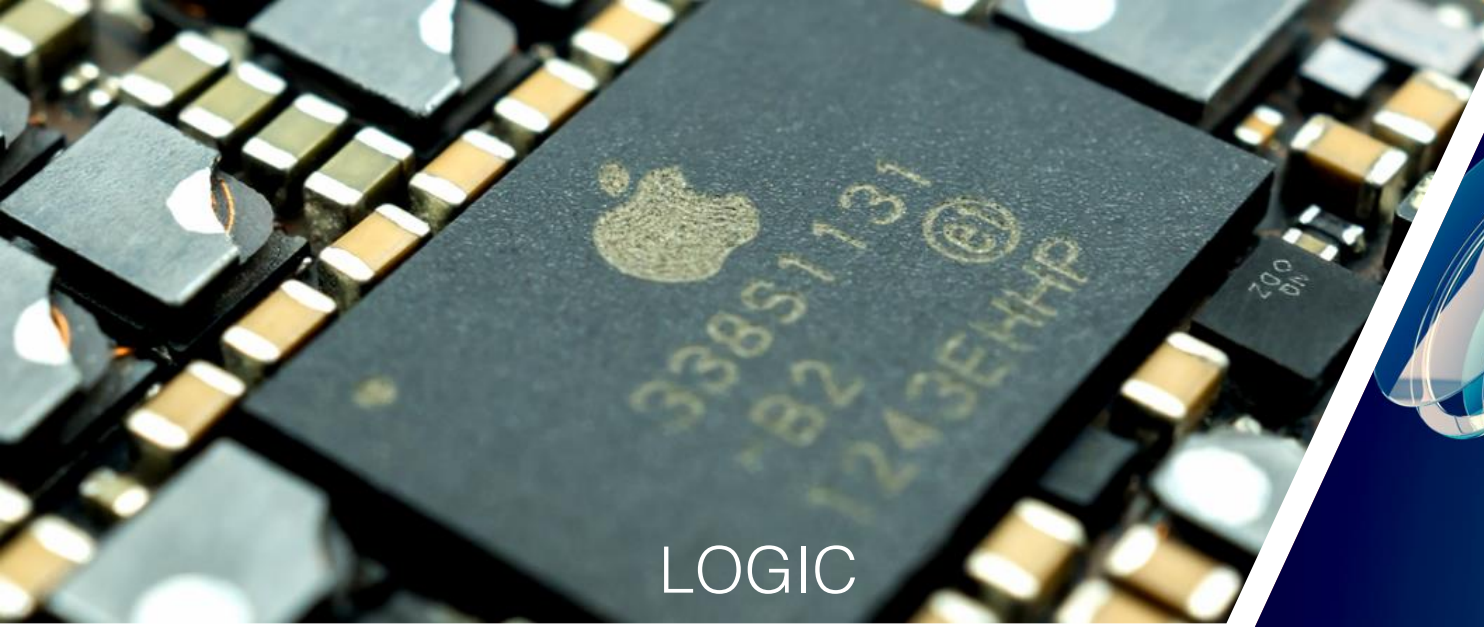
Extensive in-house
semiconductor process
testing capabilities

Class 10/100 Clean room
production

Fully audited production
track record

> 200 tons/year capacity of
high value materials

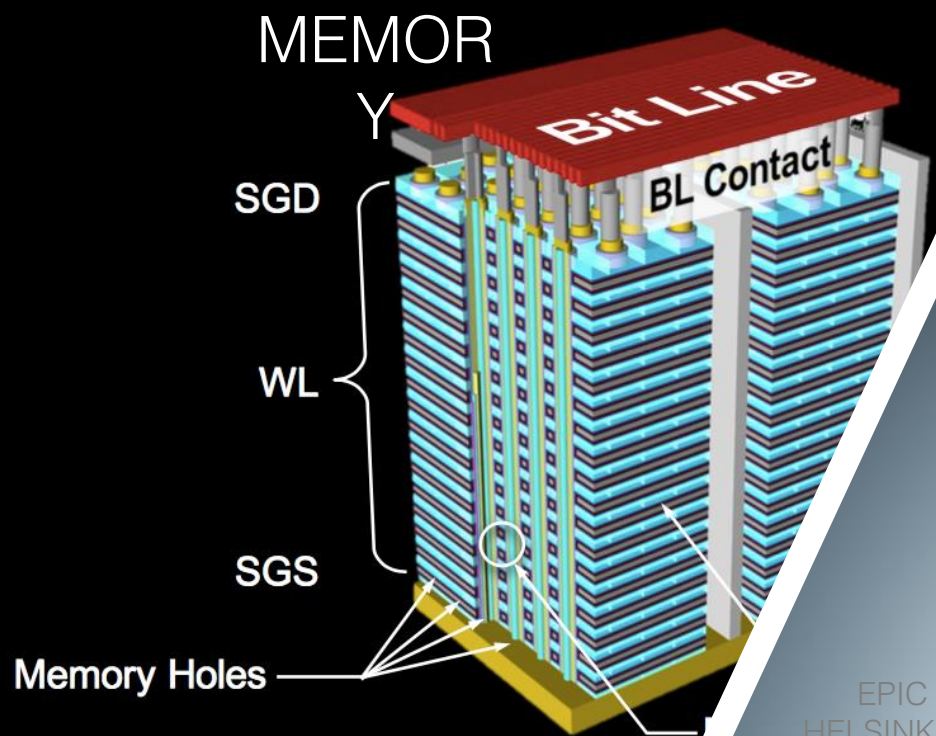




LOGIC



PHOTONIC SENSORS



MEMOR

Y

Bit Line

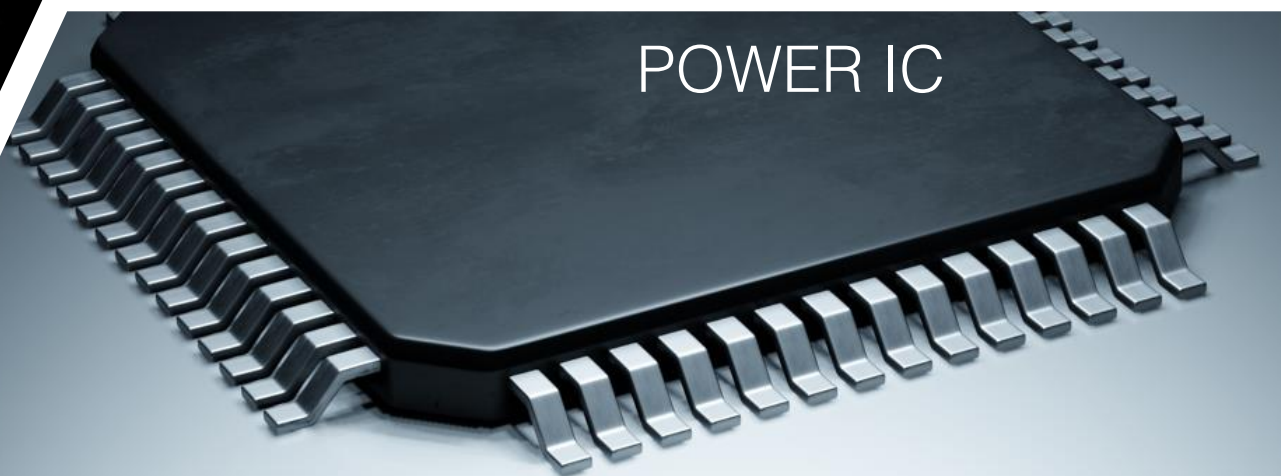
BL Contact

SGD

WL

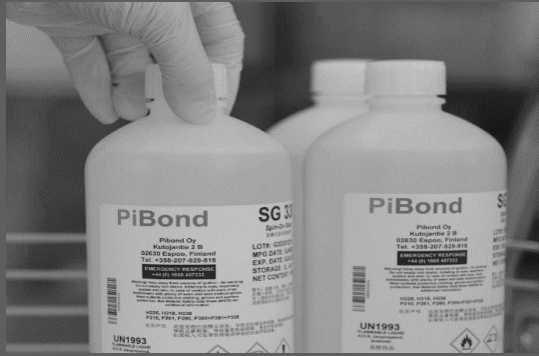
SGS

Memory Holes

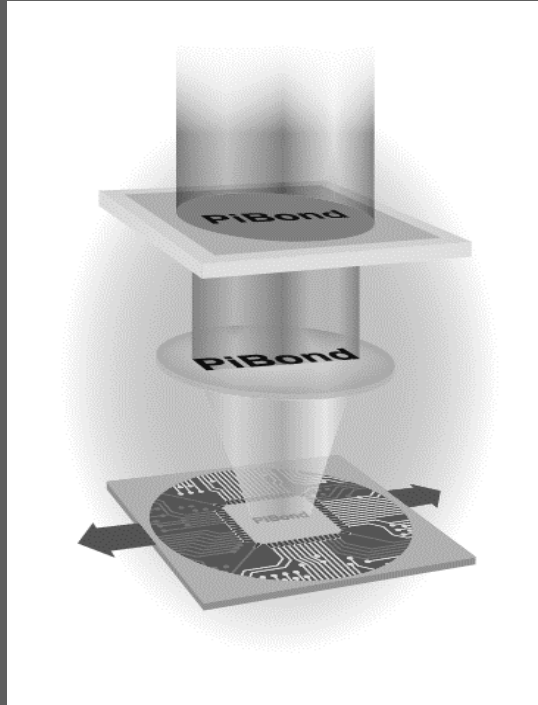


POWER IC

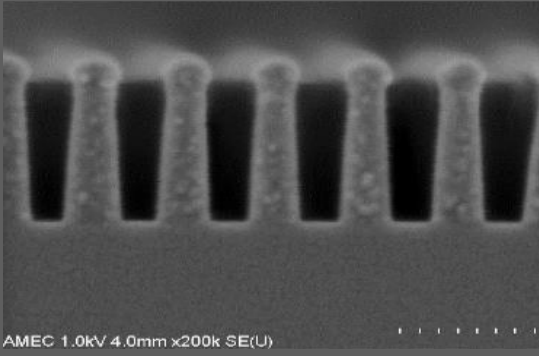
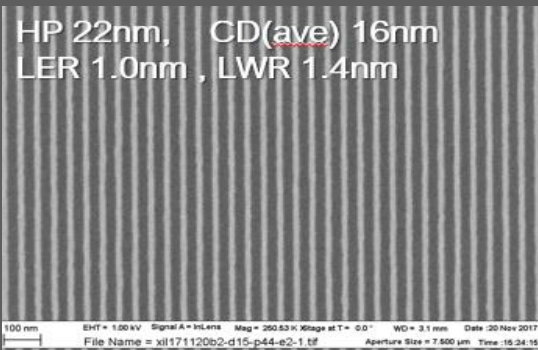
Advanced Lithography



Demand for
Inorganic solutions

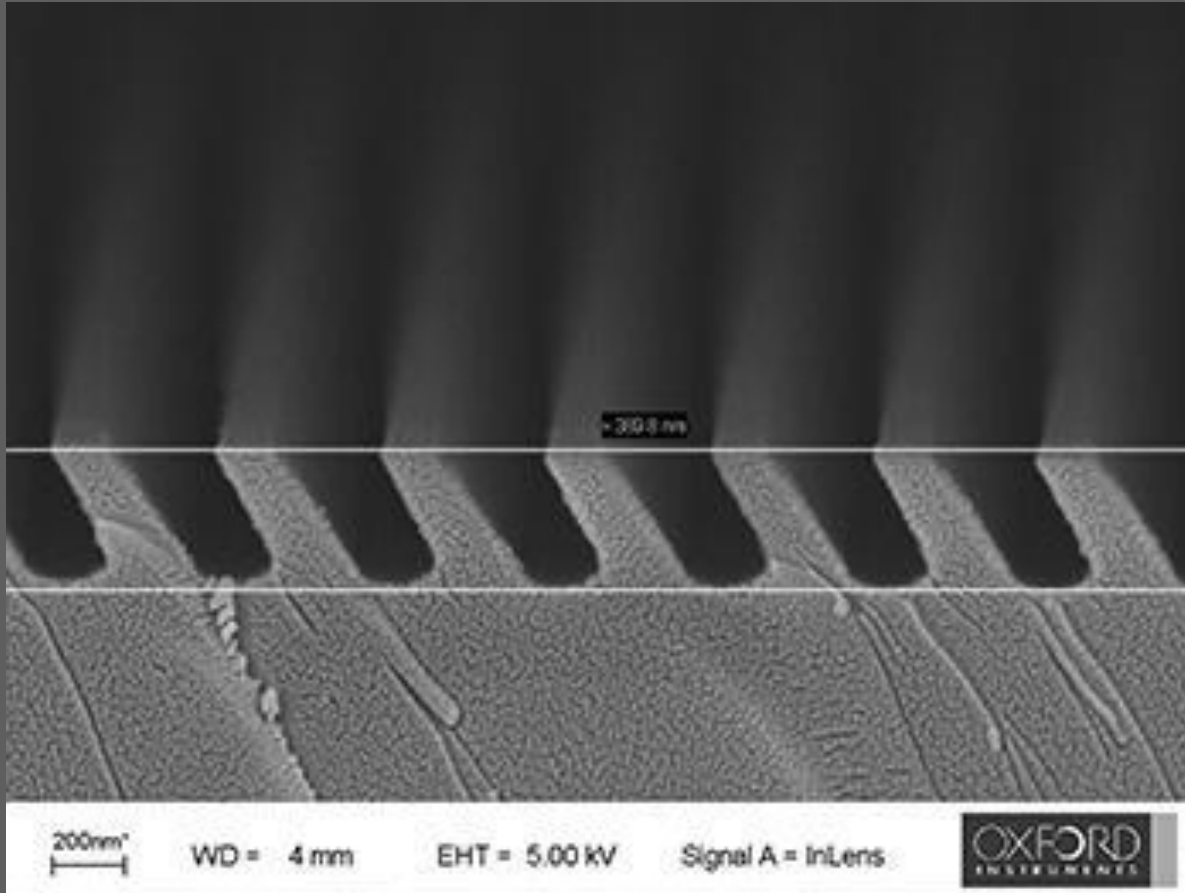


Industry proven
stack <5nm

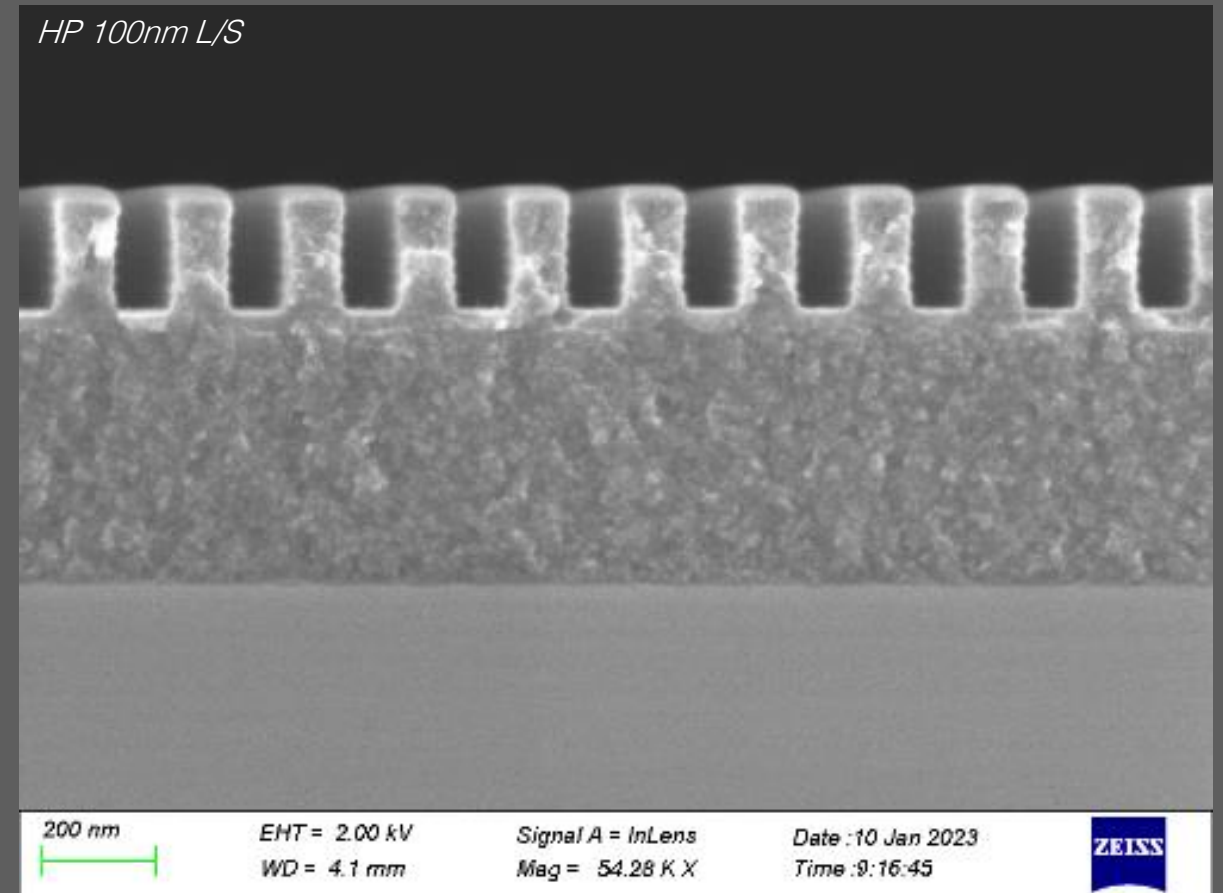


Leading Etch
selectivity for future
devices

Advanced Lithography Materials for line patterning

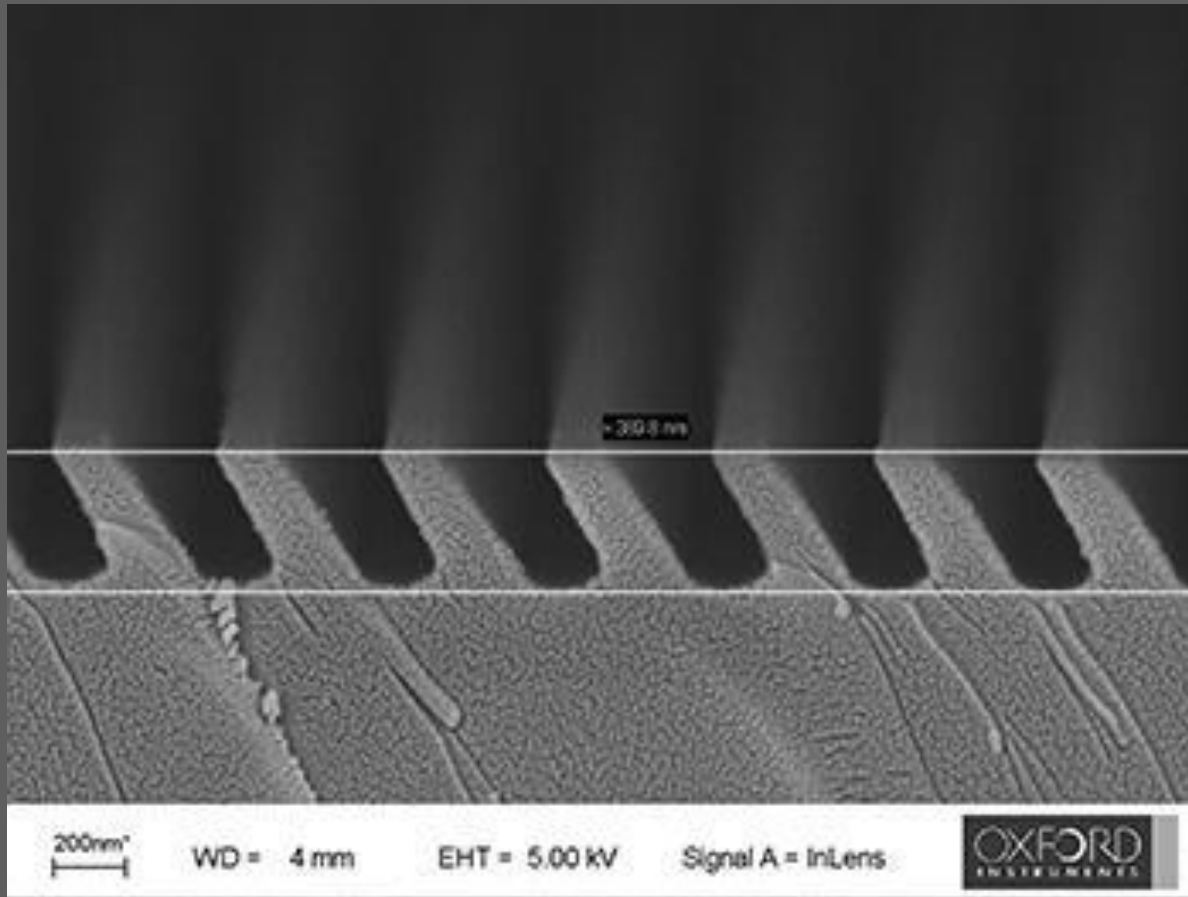


<https://plasma.oxinst.com/blog/2020/3-steps-for-surface-relief-gratings>

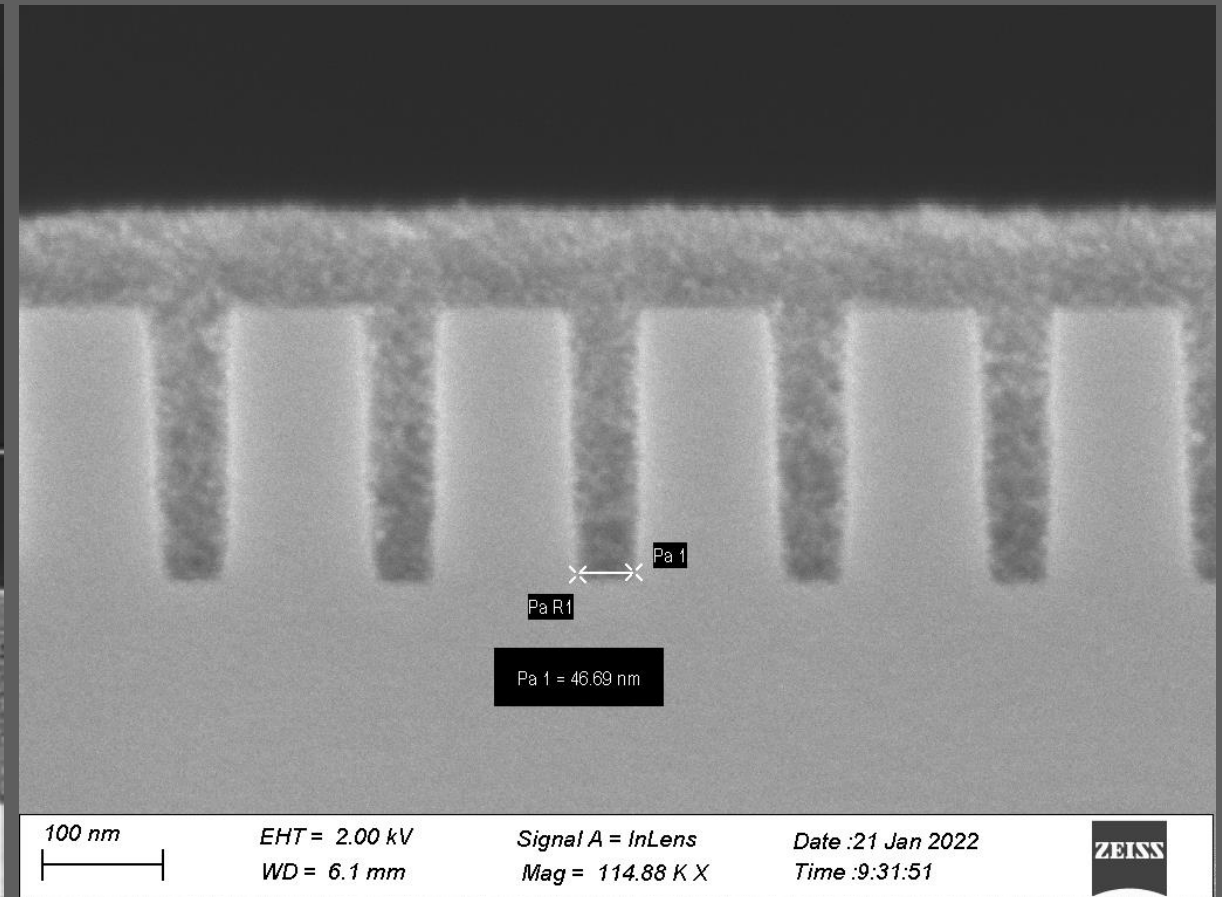


Etch hard masks and processes

Optical coatings and fill-planarization

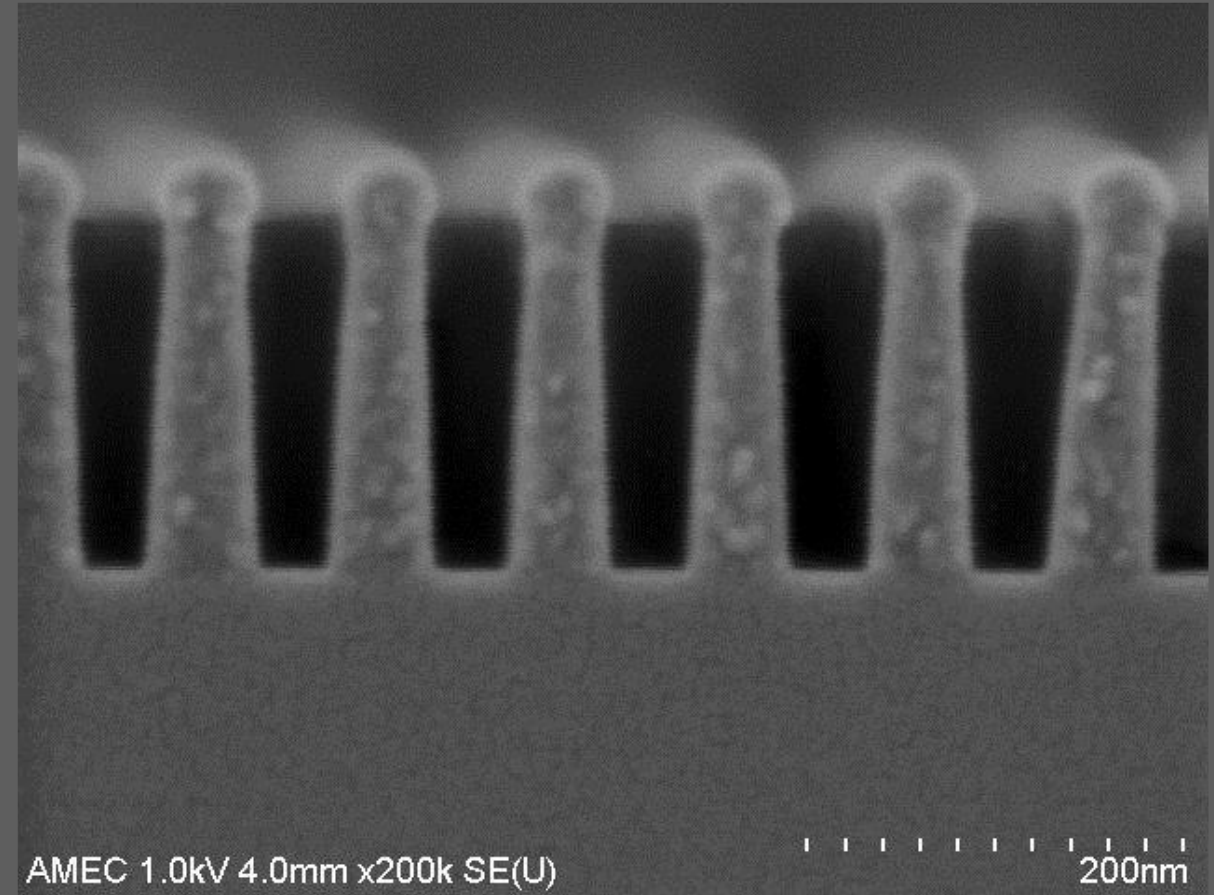
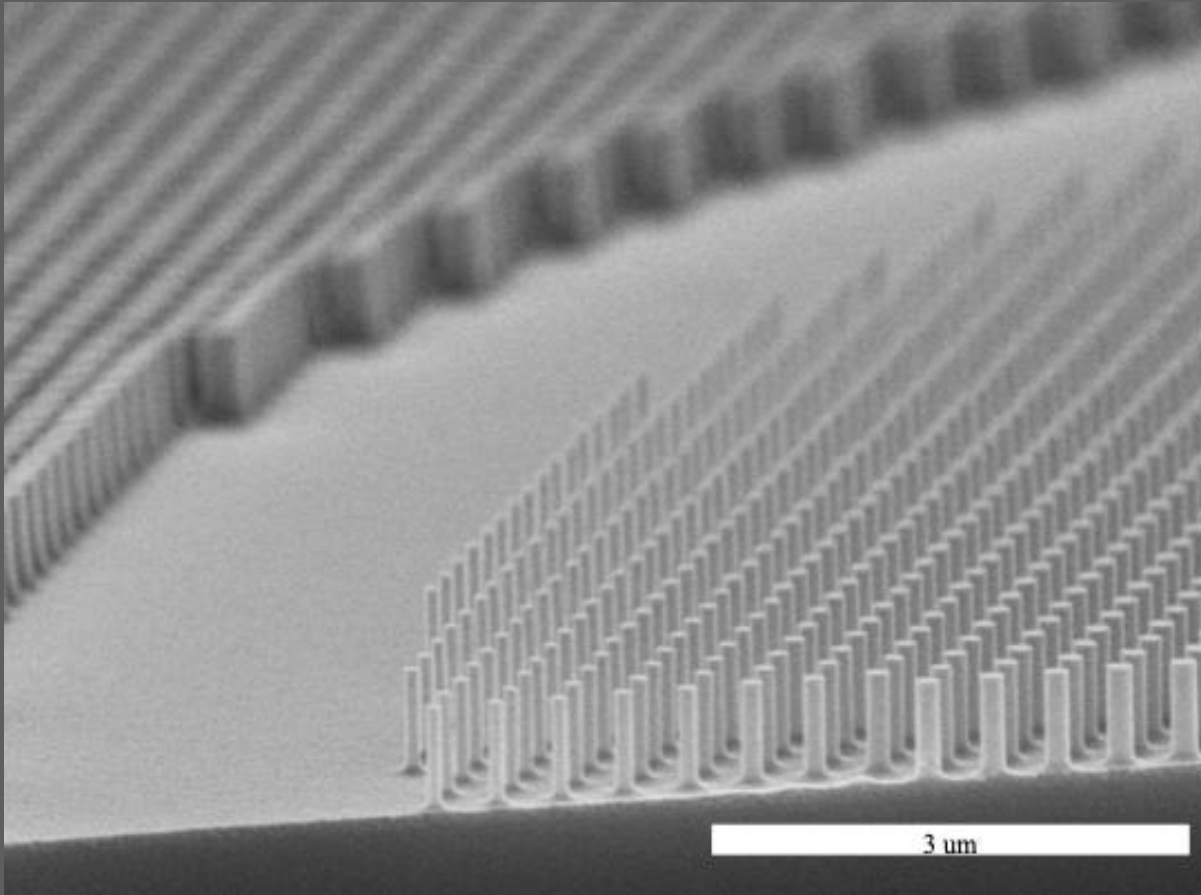


<https://plasma.oxinst.com/blog/2020/3-steps-for-surface-relief-gratings>



Variable refractive index gap fill

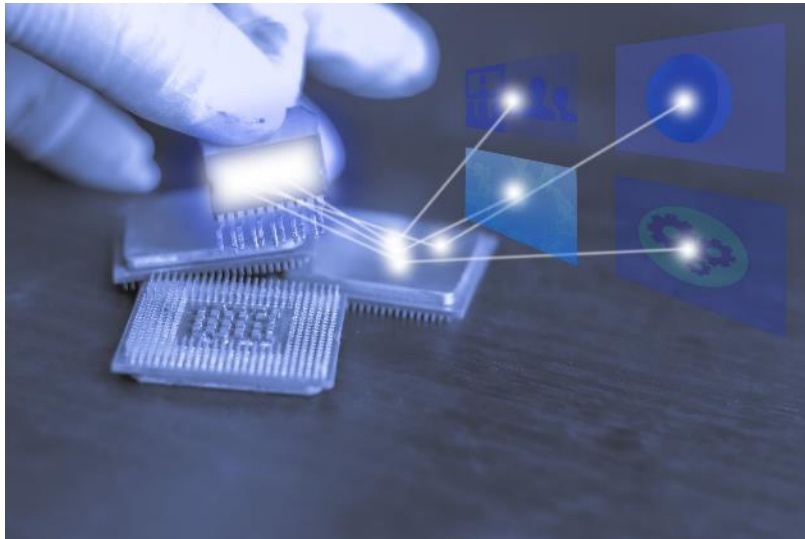
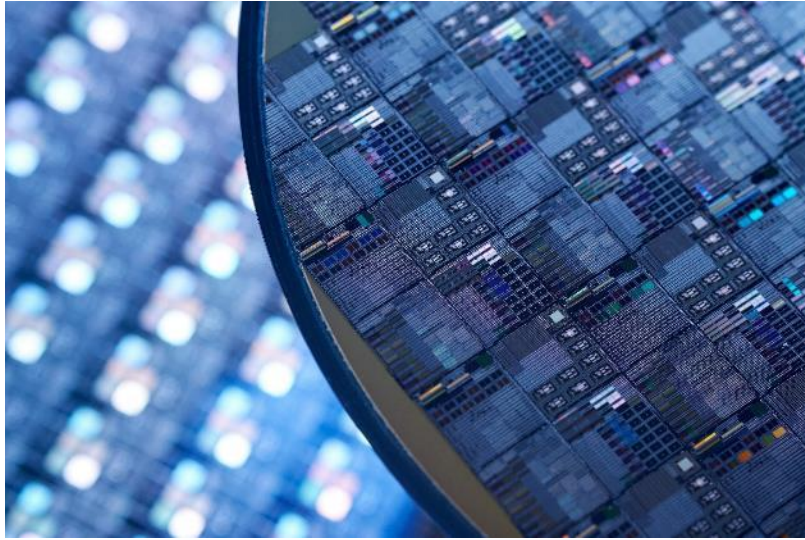
Advanced Lithography Materials for MOE



V. J. Einck, M. Torfeh, A. McClung, D. E. Jung, M. Mansouree, A. Arbabi, J. J. Watkins
ACS Photonics 2021, 8, 2400–2409

Photolithography etch hard masks

PiBond is a leading innovator of Advanced Materials



PRESENT

Semiconductor Dielectrics
for State-of-the-Art Applications

Optical Coatings for
Image Sensors

Enabling Layers for
Sub-5nm microelectronics

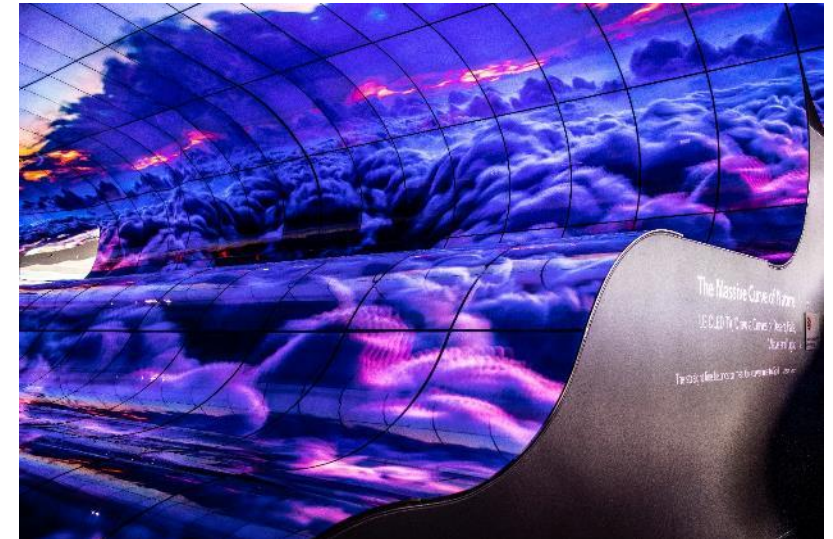


FUTURE

Future Data Transfer
Through Photonics

Semiconductor-level
Precision and Reliability
to Photonic Applications

Devices and components
enabled by novel processes



PiBond

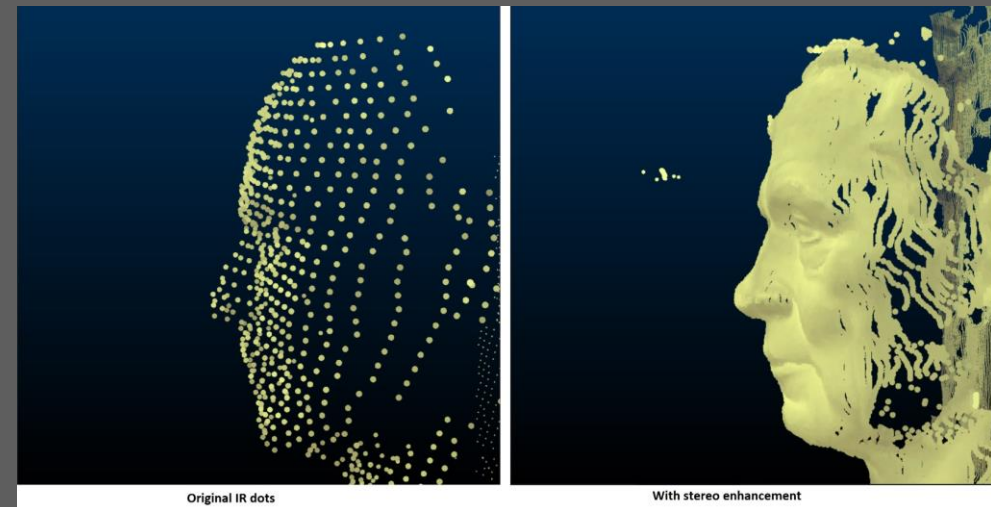
EPIC ANNUAL GENERAL MEETING
HELSINKI, FINLAND – MARCH 29-30, 2023



The most accurate 3D sensor in the world enabled by meta optics

- True scale in cartesian 3D
- High sampling rate (> 60 fps)
- Sub-mm depth resolution
- Up to 20 meters in distance

Specs and applications: www.pictm.io



An aerial photograph of a dense forest during autumn. The trees are a mix of dark green evergreens and yellow-green deciduous trees. A thick layer of white mist or fog hangs between the trees, creating a soft, ethereal atmosphere. The background shows a forested hillside under a pale sky.

Thank you

PiBond

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